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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

For: FLEXIBLE BALL GRID ARRAY
CHIP SCALE PACKAGES AND
METHODS OF FABRICATION

Confirmation No.: 5108

Examiner: S. Clark

Group Art Unit: 2815

Attorney Docket No.: 4368US (99-0959)

Notice of Allowance Mailed:

September 30, 2002

CERTIFICATE OF MAILING

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December 18, 2002
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J. McMiller
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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Box ISSUE FEE
Commissioner for Patents
Washington, D.C. 20231

Sir:

Please amend the above-referenced application as follows: